L Number	Hits	Search Text	DB	Time stamp
1	594	(257/330).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 10:47
2	288	(257/331).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 11:04
3	547	(257/341).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 11:05

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L Number	Hits	Search Text	DB	Time stamp
1	258	(257/343).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 13:07
2	691	(257/329, 332, "333").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 13:08

L Number	Hits	Search Text	DB	Time stamp
1	0	semiconductor and (plateable adj metal) and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 14:13
2	8204	semiconductor and plat$4 and metal and (gate adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 14:17
3	226	(semiconductor and plat$4 and metal and (gate adj electrode)) and (plat$4 adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 14:20

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